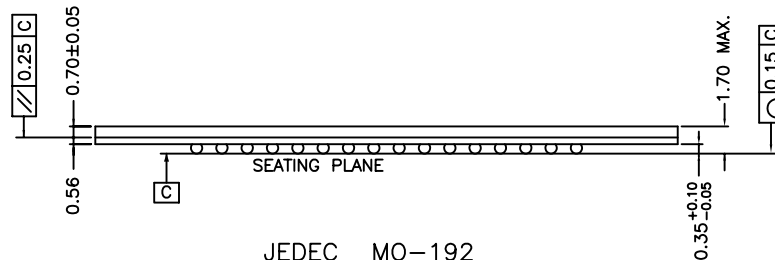
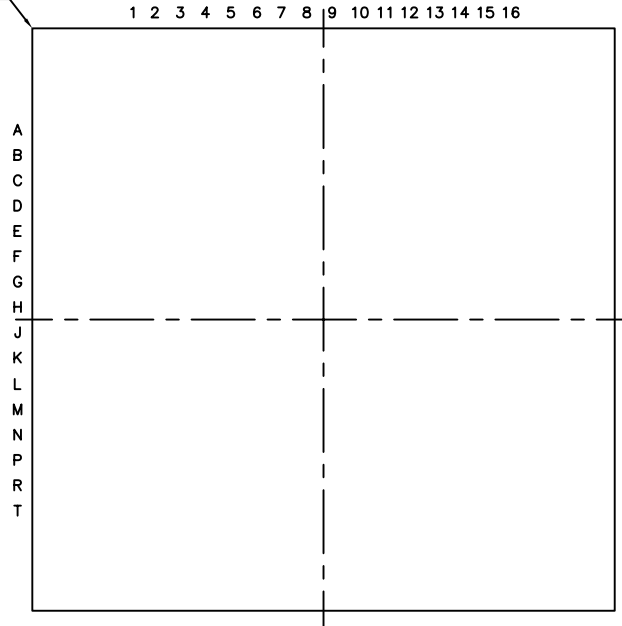


REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
1	-	**	209845	NEW RELEASE	03/10/04	N/A
1	-	*A	360958	Flatness to 0.15. Add pkg weight.	05/06/05	N/A
1	-	*B	2804553	Changed template and title from 256 FBGA 23x23x1.7MM PACKAGE OUTLINE to PACKAGE OUTLINE, 256L FBGA 23X23X1.7 MM BB256B.	11/17/09	QAD
1	-	*C	3353048	Update spec for Sunset Review, no change.	08/24/11	QAD
1	-	*D	3726611	Changed package weight from 1.2grams to "refer to PMDD spec."	08/28/12	QAD

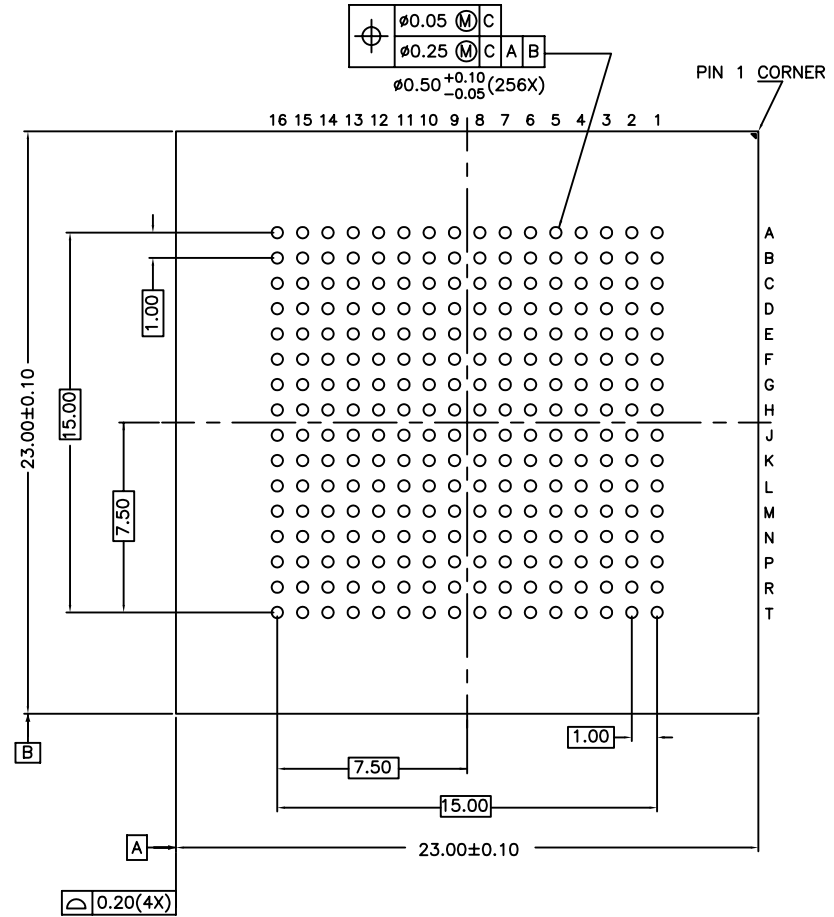
TOP VIEW


PIN 1 CORNER



JEDEC MO-192
Package Weight : Refer to PMDD spec.

BOTTOM VIEW



UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN MILLIMETERS STANDARD TOLERANCES ON: DECIMALS .XX ± 0.05 .XXX ± .XXXX + ANGLES ± 1°		DESIGNED BY MLA	DATE 05/06/05	 CYPRESS Company Confidential		
		DRAWN BY MLA	DATE 05/06/05			
		CHECKED BY XANC	DATE 08/28/12	TITLE PACKAGE OUTLINE, 256L FBGA 23X23X1.7 MM BB256B		
		APPROVED BY QAD	DATE 08/28/12			
MATERIAL N/A	APPROVED BY EDCA	DATE 08/28/12	SIZE A	PART NO. BB256B	DWG NO 51-85201	REV *D
FINISH N/A	APPROVED BY PRC	DATE 08/28/12	SCALED TO FIT N/A		SHEET 1	OF 1

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